Electronic Supplementary Material (ESI) for RSC Advances.

Development of a Nanoscale Electroless Plating Procedure for Bismuth and its Application in Template-Assisted Nanotube Fabrication

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Supporting Information

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1. Additional TEM images

Figure S1 shows a TEM image of a Pd activated membrane prior to Bi deposition. Note how the particle sizes are significantly smaller than those of the deposited Bi film, allowing for a distinction of the two layers.

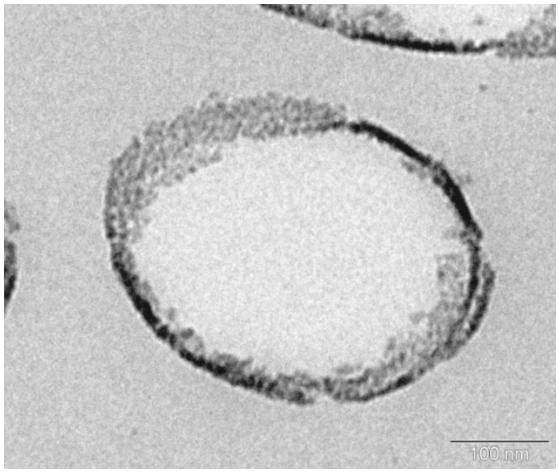

Figure S1: TEM image of a Pd-activated ion-track etched polycarbonate membrane, cut perpendicular to the pore axis.

Depositions were also carried out with higher DMAB concentration (100 mM, 120 h plating time). As an example, TEM images of the resulting deposit are shown in Figure S1, indicating that by increasing the DMAB concentration and deposition time, thicker and denser Bi deposits can be obtained (**Figure S2 a, b**)

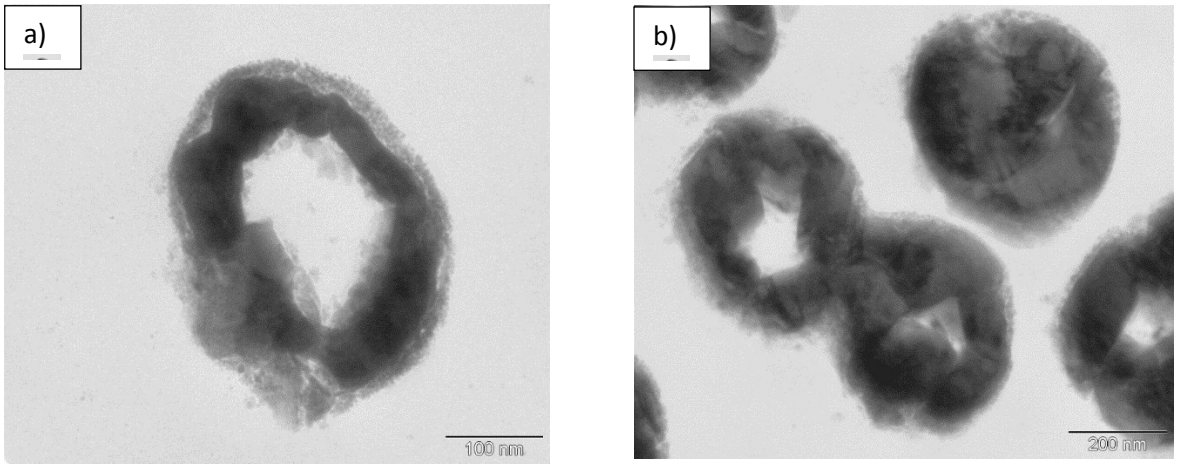

Figure S2: a, b) TEM images of cross-sections of electrolessly deposited Bi films in ion-track etched polycarbonate membranes using a higher DMAB concentration and longer plating time (100 mM DMAB, 120 h plating).